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SIMPLIFIED LOGISTICS MODEL AND ITS APPLICATION IN PROCESS SIMULATION

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Yiwei CHEN^{a*}, Guanliang DING^{b,c*}, and Yakai BAI^d
^aSchool of Journalism and Communication, Shanghai University, Nanjing, China
^bSchool of Humanities and Law, Jiaxing University, Jiaxing, China
^cChina Academy of Rural Development, Zhejiang University, Hangzhou,
Zhejiang, China
^dChinese Academy of Science, Beijing, China

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*Corresponding author, e-mail: cyw169480@163.com

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Correct affiliation of the 1st author Yiwei CHEN is as it is written below:

^aSchool of Economics and Management, Southeast University, Nanjing, China